4,194,304-words × 1-bit High Speed Static Random Access Memory

# HITACHI

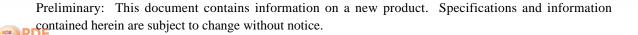
ADE-203-086G(Z) Rev. 8 Aug. 28, 1996

#### **Features**

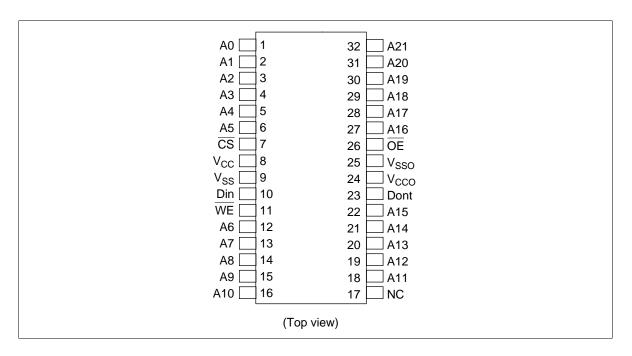
- 4194304-words  $\times 1$  bit organization
- Directly TTL compatible input and output
- +5.0 V Single Supply
- Completely static memory
- No clock or timing strobe required
- Super fast access time: 15/20 ns (Max)
- Revolutional Pin Arrangement

#### **Ordering Information**

Type No.	Organization	Access time	Package	
HM671400HJP-15		15 ns	400 mil 32 pin	
HM671400HJP-20	4M×1	20 ns	Plastic SOJ (CP-32DB)	



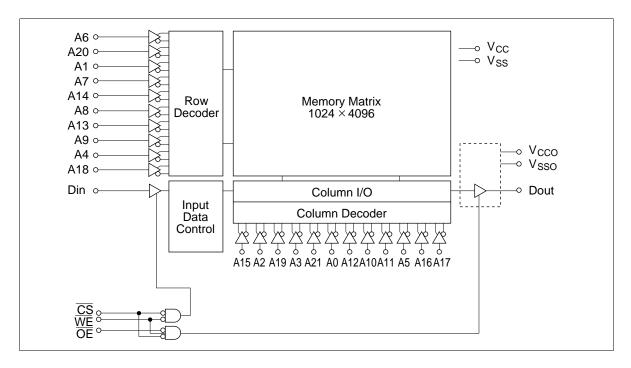
### **Pin Arrangement**



### **Pin Description**

Pin Name	Function
A0 to A21	Address Input
Din	Data Input
Dout	Data Output
WE	Write Enable
CS	Chip Select
ŌĒ	Output Enable
V <sub>cc</sub>	+5 V Power Supply
V <sub>cco</sub>	Output Buffer Power Supply
V <sub>SSO</sub>	Output Buffer Ground
V <sub>SS</sub>	Ground
NC	Not Connect

### **Block Diagram**



#### **Function Table**

CS	WE	OE	Mode	Output	V <sub>cc</sub> Current
Н	Χ	Χ	Not Selected	High Z	I <sub>SB</sub> , I <sub>SB1</sub>
L	Н	Н	Output Disable	High Z	I <sub>CC</sub> , I <sub>CC1</sub>
L	Н	L	Read	Data Out	I <sub>CC</sub> , I <sub>CC1</sub>
L	L	Н	Write	High Z	I <sub>CC</sub> , I <sub>CC1</sub>
L	L	L	Write	High Z	I <sub>CC</sub> , I <sub>CC1</sub>

#### **Absolute Maximum Ratings**

Item	Symbol	Rating	Unit
Supply Voltage *1	V <sub>cc</sub>	-0.5 to + 7.0	V
Voltage on any pin relative to V <sub>SS</sub> *1	V <sub>T</sub>	$-0.5$ to $V_{cc} + 0.5$	V
Power dissipation	P <sub>T</sub>	1.0/1.5 *2	W
Operating Temperature Range	Topr	0 to +70	°C
Storage Temperature Range (with bias)	Tstg (Bias)	-10 to + 85	°C
Storage Temperature Range	Tstg	-55 to + 125	°C

Notes: 1. With respect to  $V_{ss} = V_{sso}$ 

Under the dc and ac specifications shown in the Tables, this device is tested under the minimum transverse air flow exceeding 500 linear feet per minute.

### **Recommended DC Operating Conditions** $(0^{\circ}C \le Ta \le 70^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit
Supply Voltage	$V_{cc}, V_{cco}$	4.5	5.0	5.5	V
	$V_{SS}$ , $V_{SSO}$	0.0	0.0	0.0	V
Input High Voltage	$V_{IH}$	2.2	_	$V_{cc}$ + 0.5	V
Input Low Voltage	$V_{IL}$	-0.5	_	0.8	V

<sup>2.</sup>  $P_T = 1.5$  W is guaranteed under the minimum air flow exceeding 500 linear feet per minute.

DC and Operating Characteristics (V $_{CC}$  = V $_{CCO}$  = 5.0 V  $\pm$  10%, V $_{SS}$  = V $_{SSO}$  = 0 V, Ta = 0 to +70°C)

				15		20	
Item	Symbol	Test Conditions	Min	Max	Min	Max	Unit
Input Leakage Current	II <sub>u</sub> I	$V_{CC} = 5.5 \text{ V},$ $V_{IN} = 0 \text{ V to } V_{CC}$	_	2	_	2	μΑ
Output Leakage Current	II <sub>LO</sub> I		_	10	_	10	μΑ
Operating Power Supply Current	I <sub>cc</sub>	$\overline{\text{CS}} = V_{\text{IL}}, I_{\text{OUT}} = 0 \text{ mA}$	_	120	_	120	mA
Average Operating Current	I <sub>CC1</sub>	Min. cycle, $I_{OUT} = 0 \text{ mA}$		170	_	150	mA
Standby Power Supply Current	I <sub>SBAC</sub>	$\overline{\text{CS}} = V_{IH} \text{ Min. cycle}$	_	100	_	80	mA
	I <sub>SBDC</sub>	$\overline{\text{CS}} = V_{\text{IH}}$ All input fixed and $V_{\text{IN}} = V_{\text{IH}}$ or $V_{\text{IL}}$	_	20	_	20	mA
	I <sub>SB1</sub>	$\overline{CS} \ge V_{CC} - 0.2 \text{ V}$ $V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$	_	10	_	10	mA
Output Low Voltage	$V_{OL}$	$I_{OL} = 8 \text{ mA}$		0.4		0.4	V
Output High Voltage	V <sub>OH</sub>	$I_{OH} = -4 \text{ mA}$	2.4		2.4	_	V

AC Characteristics ( $V_{CC} = V_{CCO} = 5.0 \ V \pm 10\%$ ,  $V_{SS} = V_{SSO} = 0 \ V$ , Ta = 0°C to 70°C, unless otherwise noted.)

#### **Read Cycle**

			15		20	
Item	Symbol	Min	Max	Min	Max	Unit
Read Cycle Time	t <sub>RC</sub>	15	_	20	_	ns
Address Access Time	t <sub>AA</sub>	_	15	_	20	ns
Chip Select Access Time	$t_{\sf ACS}$	_	15	_	20	ns
Chip Selection to Output in Low Z	$t_{LZ}$ *1, *2	5	_	5	_	ns
Output Enable to Output Valid	t <sub>OE</sub>	_	8	_	10	ns
Output Enable to Output in Low Z	$t_{\text{OLZ}}$ *1, *2	2	_	2	_	ns
Chip Deselection to Output in High Z	t <sub>HZ</sub> *1, *2	0	7	0	8	ns
Output Hold from Address Change	t <sub>oh</sub>	5	_	5	_	ns

Notes: 1. This parameter is sampled and not 100% tested.

2. Transition is measured  $\pm 200$  mV from steady state voltage with specified loading in Load(B).

#### Write Cycle

			15		20	
Item	Symbol	Min	Max	Min	Max	Unit
Write Cycle Time	t <sub>wc</sub> *1	15	_	20	_	ns
Chip Selection to End of Write	t <sub>cw</sub>	12	_	15	_	ns
Address Valid to End of Write	t <sub>AW</sub>	12	_	15	_	ns
Address Setup Time	t <sub>AS</sub>	0	_	0	_	ns
Write Pulse Width	t <sub>WP</sub>	12	_	15	_	ns
Write Recovery Time	t <sub>WR</sub>	3	_	3	_	ns
Data Valid to End of Write	t <sub>DW</sub>	8	_	10	_	ns
Data Hold Time	t <sub>DH</sub>	0	_	0	_	ns
Write Enable to Output in High Z	t <sub>wz</sub> *2, *3	0	7	0	8	ns
Output Disable to Output in High Z	t <sub>OHZ</sub> *2, *3	0	7	0	8	ns
Output Active from End of Write	t <sub>OW</sub> *2, *3	2	_	2	_	ns

Notes: 1. All Write Cycle timings are referenced from the last valid address to the first transitioning address.

2. This parameter is sampled and not 100% tested.

3. Transition is measured ±200 mV from steady state voltage with specified with loading Load(B).

#### **Capacitance** (Ta = 25°C, f = 1 MHz)

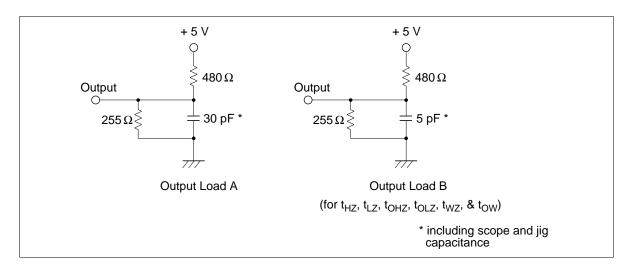
Item	Symbol	Max	Unit	Test Condition
Input Capacitance	C <sub>IN</sub> *1	6	pF	$V_{IN} = 0 V$
Output Capacitance	C <sub>OUT</sub> *1	8	pF	$V_{OUT} = 0 V$

Note: 1. This parameter is sampled and not 100% tested.

#### **AC Test Conditions**

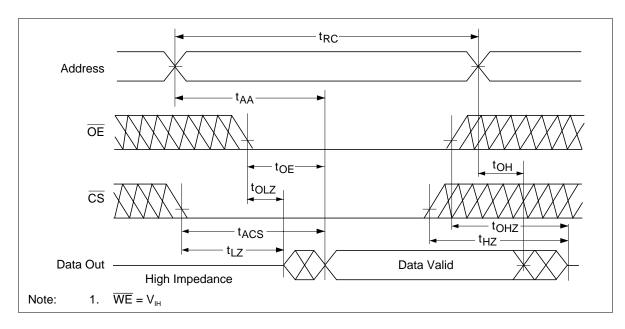
Input pulse levels: V<sub>SS</sub> to 3.0 V
Input timing reference levels: 1.5 V

Output Load: See figure
Input rise and fall times: 4 ns
Output reference levels: 1.5 V

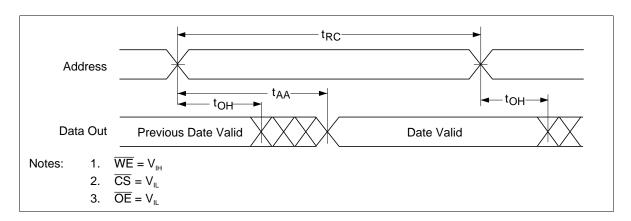


## **Timing Waveforms**

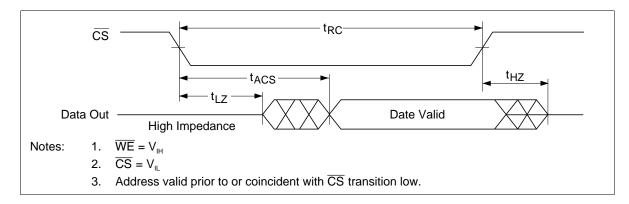
#### Read Cycle-1 \*1



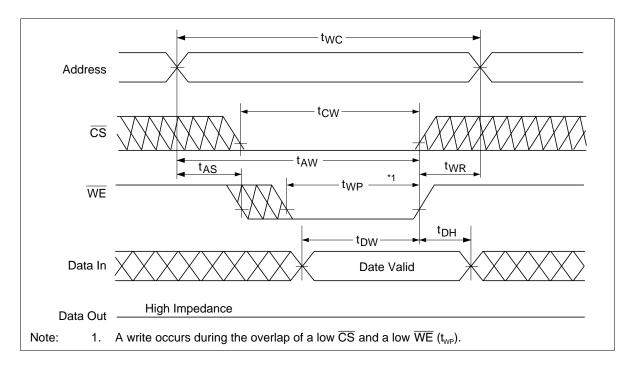
## **Read Cycle-2** \*1, \*2, \*3



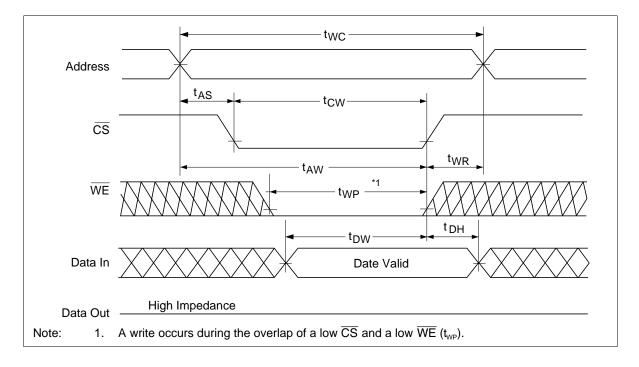
#### Read Cycle-3 \*1, \*2, \*3



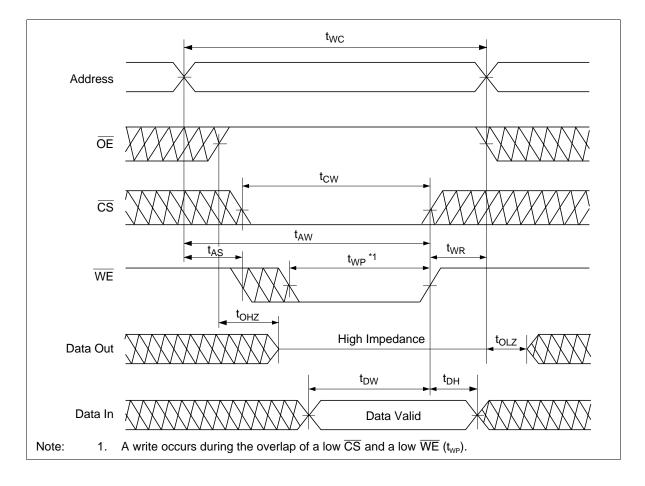
### Write Cycle-1 \*1 ( $\overline{OE} = H$ , $\overline{WE}$ Controlled)



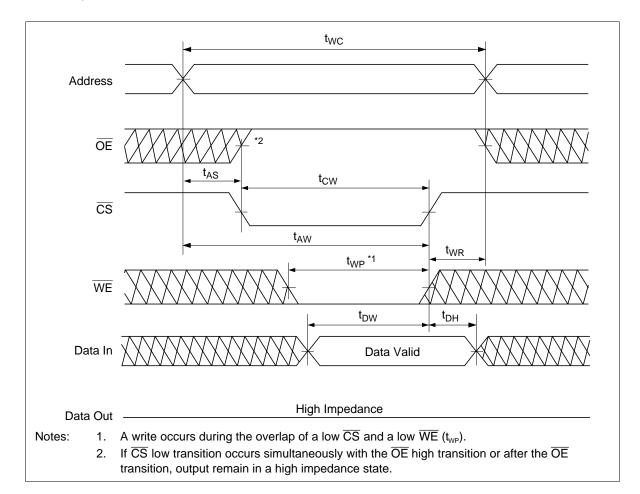
Write Cycle-2 \*1 ( $\overline{OE} = H$ ,  $\overline{CS}$  Controlled)



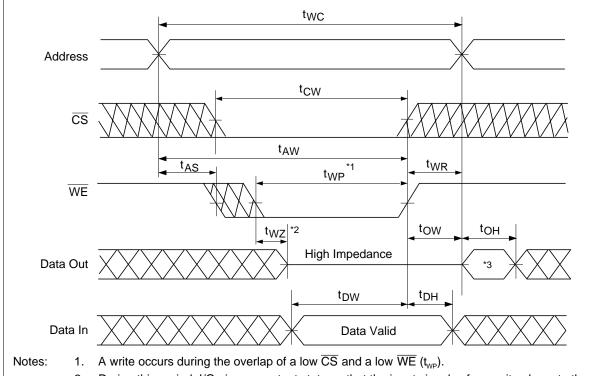
## Write Cycle-3 \*1 ( $\overline{OE}$ = Clocked, $\overline{WE}$ Controlled)



Write Cycle-4 \*1, \*2 ( $\overline{OE}$  = Clocked,  $\overline{CS}$  Controlled)

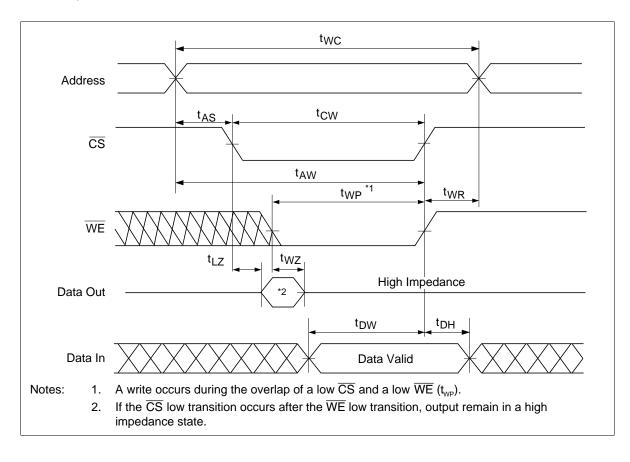


Write Cycle-5 \*1, \*2, \*3 ( $\overline{OE} = L$ ,  $\overline{WE}$  Controlled)



- 2. During this period, I/O pins are output state so that the input signals of opposite phase to the outputs must nit be applied.
- 3. Output data is the same phase of write data of this write cycle.

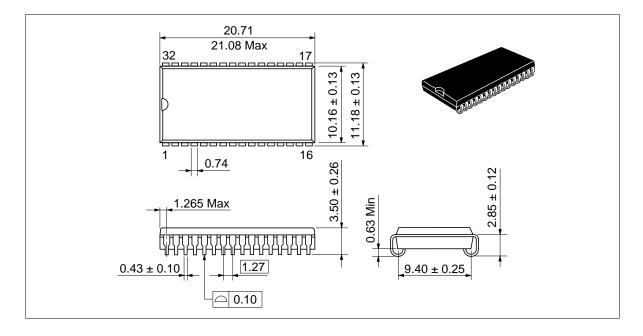
Write Cycle-6 \*1, \*2 ( $\overline{OE} = L$ ,  $\overline{CS}$  Controlled)



## **Package Dimension**

HM761400HJP Series (CP-32DB)

Unit: mm



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